

SMD Power Inductor

TMPA1004S-Series(N)-D

1. Features

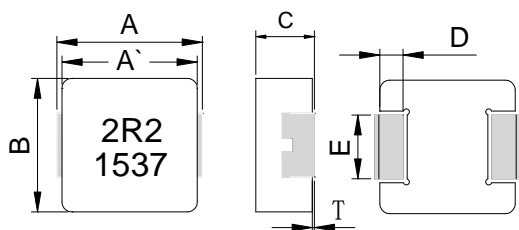
1. Shielded construction.
2. Capable of corresponding high frequency (5MHz).
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.



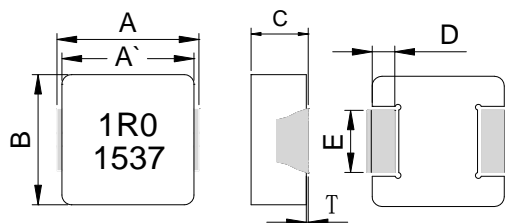
2. Applications

1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

3. Dimensions



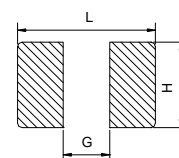
leadframe



non-leadframe



Recommend PC Board Pattern



Series	A	A'	B	C	D	T	E	Inductance
TMPA1004	11.0±0.3	10.0±0.3	10.0±0.3	3.8±0.2	2.0±0.3	0~0.2	2.5±0.3	0.56~1.50uH among
							3.0±0.3	0.47uH and below 2.20uH and above

Unit: mm

L(mm)	G(mm)	H(mm)
12.5	5.4	3.5

Note:

1. Only for reference.
2. Recommend solder paste thickness at 0.15mm and above

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: Code
- BxC
Standard.
R10=0.1uh, 1R0=1.0uh, 100=10uh, 101=100uh, 102=1000uh.
K=±10%, L=±15%, M=±20%, N=±25%, Y=±30%
Marking: Black.1R0 and 1537(15 YY, 37 WW, follow production date).

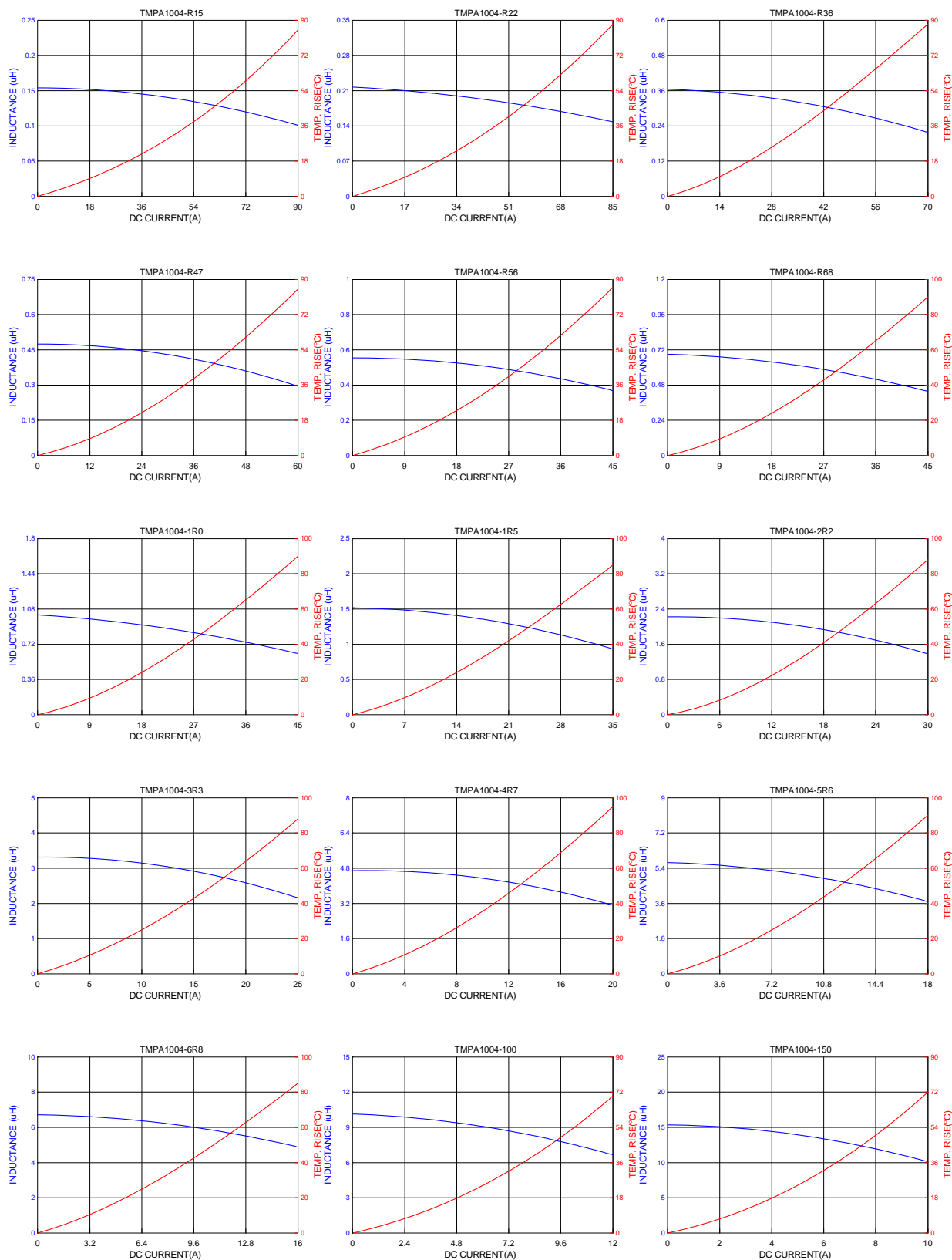
5. Specification

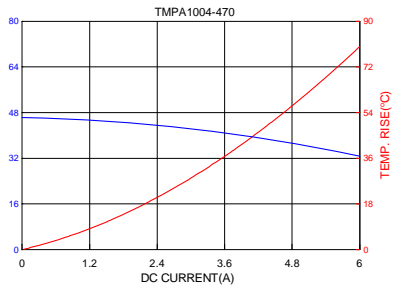
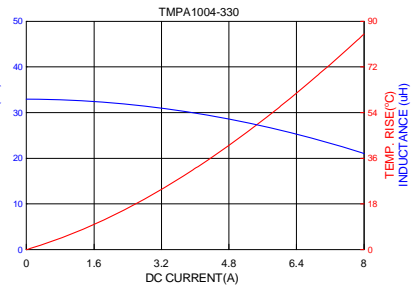
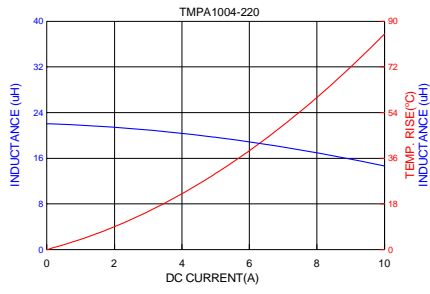
Part Number	Inductance L0 A(μH) ±20%	Heat Rating Current DC I rms.(A)		Saturation Current DC I sat. (A)		DCR (mΩ)Typ	DCR (mΩ)Max	Type
		Typ	Max	Typ	Max			
TMPA1004S-R15YN-D	0.15±30%	44	38	82	75	0.5	0.6	non-leadframe
TMPA1004S-R22MN-D	0.22	36	33	70	60	0.72	0.83	non-leadframe
TMPA1004S-R36MN-D	0.36	33	29	51	45	1.05	1.18	non-leadframe
TMPA1004S-R47MN-D	0.47	32	28	46	40	1.3	1.5	non-leadframe
TMPA1004S-R56MN-D	0.56	25	23	34	29	1.6	1.8	non-leadframe
TMPA1004S-R68MN-D	0.68	23	20	31	28	1.9	2.2	non-leadframe
TMPA1004S-1R0MN-D	1.00	20	18	29	26	2.9	3.25	non-leadframe
TMPA1004S-1R5MN-D	1.50	17.5	16	26	22	3.7	4.2	non-leadframe
TMPA1004S-2R2MN-D	2.20	15	13	20	16	5.8	6.7	leadframe
TMPA1004S-3R3MN-D	3.30	11	10	17.5	14	10.5	11.8	leadframe
TMPA1004S-4R7MN-D	4.70	8.8	8	15.2	13	15.8	19	leadframe
TMPA1004S-5R6MN-D	5.60	8	7.2	14.1	11.5	19	22.8	leadframe
TMPA1004S-6R8MN-D	6.80	7.8	6.8	12.2	11	22	24.5	leadframe
TMPA1004S-100MN-D	10.0	7.5	6.1	8.6	7.5	27	30	leadframe
TMPA1004S-150MN-D	15.0	6.25	5	7	6	41	45	leadframe
TMPA1004S-220MN-D	22.0	5	4.1	6.2	5.5	58	66	leadframe
TMPA1004S-330MN-D	33.0	4.4	3.5	5.5	5	84	91	leadframe
TMPA1004S-470MN-D	47.0	3.5	3	4	3.7	125	143	leadframe

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves





SMD Power Inductor

TMPA1205SP-Series(N)-D

1. Features

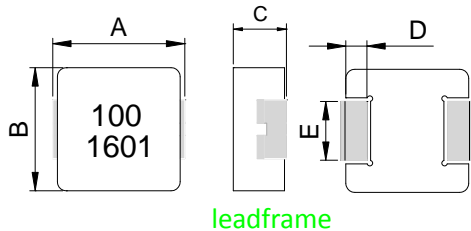
1. Shielded construction.
2. Capable of corresponding high frequency (5MHz).
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.



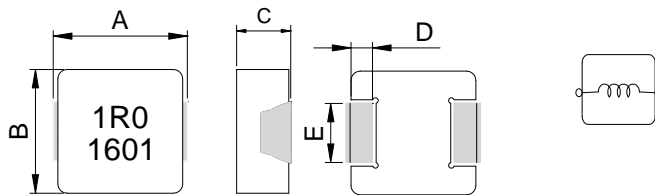
2. Applications

1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

3. Dimensions

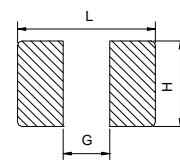


leadframe



non-leadframe

Recommend PC Board Pattern



Series	A	B	C	D	E	Inductance
TMPA1205	13.5±0.5	12.6±0.2	4.7±0.3	2.3±0.3	4.0±0.3	1.0uH and below
					4.7±0.3	1.5uH and above

Unit:mm

L(mm)	G(mm)	H(mm)
14.5	8.0	5.0

Note: Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: Code
- BxC.
Standard.
R10=0.1uh, 1R0=1.0uh, 100=10uh, 101=100uh, 102=1000uh.
K=±10%, L=±15%, M=±20%, N=±25%, Y=±30%
Marking: Black.100 and 1601(16 YY, 01 WW, follow production date).

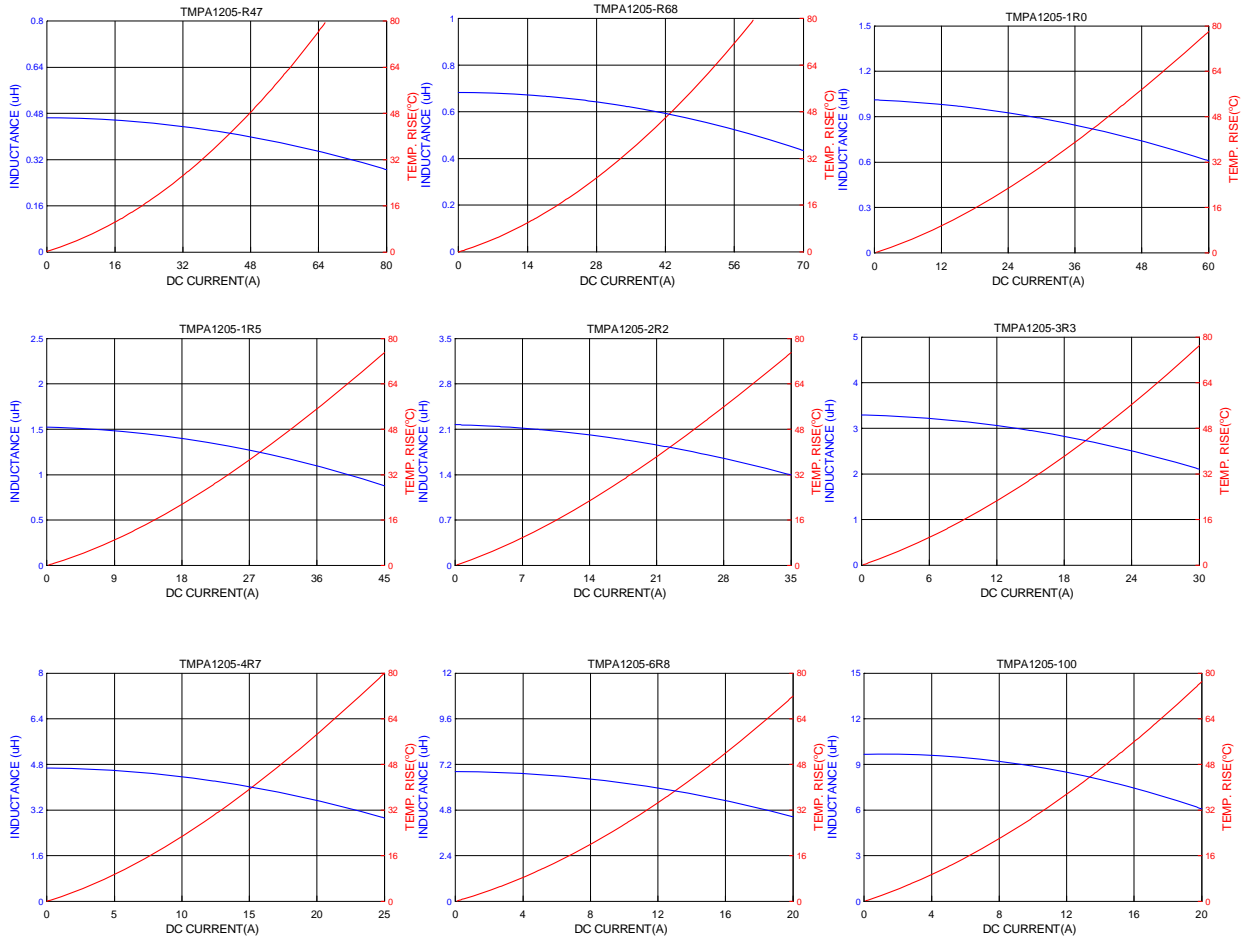
5. Specification

Part Number	Inductance L0 A(uH) ±20%	Heat Rating Current DC (A) Irms.		Saturation Current DC (A)I sat		DCR (mΩ) Typ	DCR (mΩ) Max	Type
		Typ	Max	Typ	Max			
TMPA1205SP-R47MN-D	0.47	38	34	65	58	0.77	0.9	non-leadframe
TMPA1205SP-R68MN-D	0.68	34	31	50	42	1.3	1.55	non-leadframe
TMPA1205SP-1R0MN-D	1.00	30	27	40	34	1.6	1.9	non-leadframe
TMPA1205SP-1R5MN-D	1.50	25	22	31	28	3.2	3.8	leadframe
TMPA1205SP-2R2MN-D	2.20	17	15.5	26	23	4.1	4.8	leadframe
TMPA1205SP-3R3MN-D	3.30	15.5	14	23	20.5	6.0	7.0	leadframe
TMPA1205SP-4R7MN-D	4.70	14	12.5	18.5	16	8.8	10.2	leadframe
TMPA1205SP-6R8MN-D	6.80	12	11	16.5	15	13	16	leadframe
TMPA1205SP-100MN-D	10.0	10	9.0	13	10.5	19.2	22	leadframe

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves



SMD Power Inductor

TMPA1206SP-Series(N)-D

1. Features

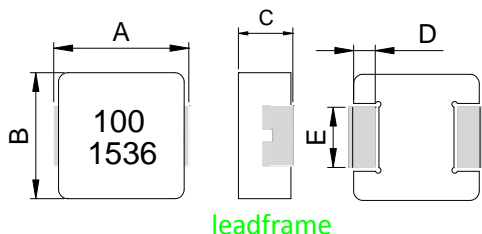
1. Shielded construction.
2. Capable of corresponding high frequency (5MHz).
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.



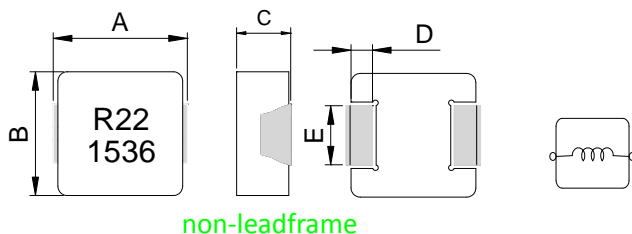
2. Applications

1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

3. Dimensions



leadframe

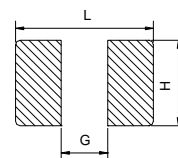


non-leadframe

Series	A	B	C	D	E
TMPA1206	13.5±0.5	12.6±0.2	5.7±0.3	2.3±0.3	4.7±0.3

Unit:mm

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
14.5	8.0	5.0

Note: Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: Code
- BxC.
Standard.
R10=0.1uh, 1R0=1.0uh, 100=10uh, 101=100uh, 102=1000uh.
K=±10%, L=±15%, M=±20%, N=±25%, Y=±30%
Marking: Black.100 and 1536(15 YY, 36 WW, follow production date).

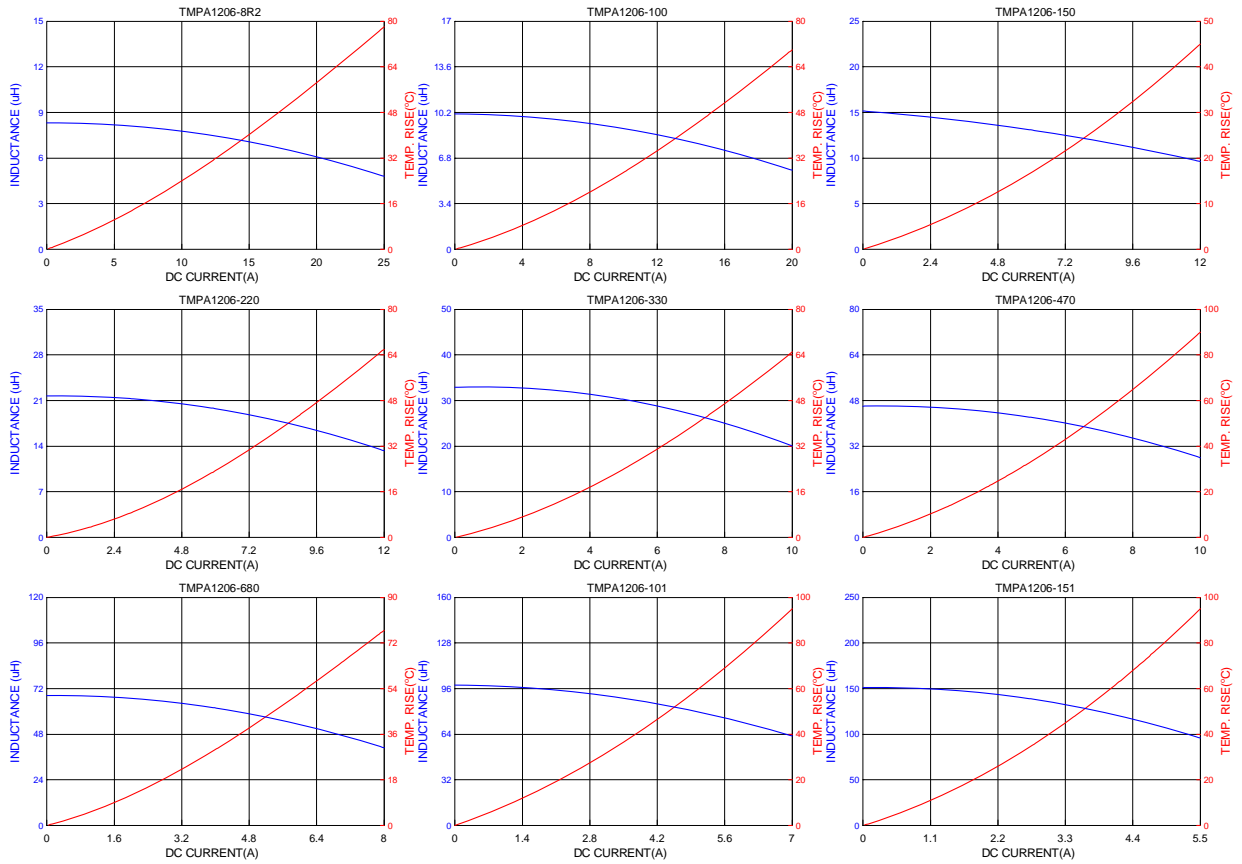
5. Specification

Part Number	Inductance L0 A(uH) ±20%	Heat Rating Current DC (A) Irms.		Saturation Current DC (A)I sat		DCR (mΩ) Typ	DCR (mΩ) Max	Type
		Typ	Max	Typ	Max			
TMPA1206SP-8R2MN-D	8.20	13.5	12.0	17.0	15.5	13.5	16.0	leadframe
TMPA1206SP-100MN-D	10.0	12.0	10.5	16.0	14.5	15.5	18.6	leadframe
TMPA1206SP-150MN-D	15.0	10.0	8.50	10.0	9.00	24.0	29.0	leadframe
TMPA1206SP-220MN-D	22.0	8.00	7.00	9.00	8.00	31.2	37.5	leadframe
TMPA1206SP-330MN-D	33.0	6.50	5.50	7.80	6.70	56.0	68.0	leadframe
TMPA1206SP-470MN-D	47.0	5.20	4.50	6.70	5.50	76.0	88.0	leadframe
TMPA1206SP-680MN-D	68.0	4.50	3.70	5.80	5.00	103	124	leadframe
TMPA1206SP-101MN-D	100	3.20	2.80	5.00	4.00	162	195	leadframe
TMPA1206SP-151MN-D	150	2.60	2.20	4.10	3.20	270	325	leadframe

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves



SMD Power Inductor

TMPA1707SP-Series(N)-D

1. Features

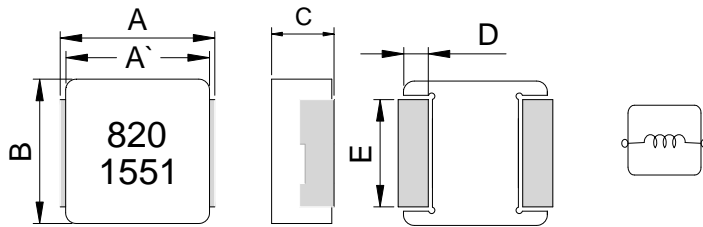
1. Shielded construction.
2. Capable of corresponding high frequency (5MHz).
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.



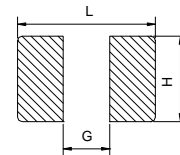
2. Applications

1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

3. Dimensions



Recommend PC Board Pattern



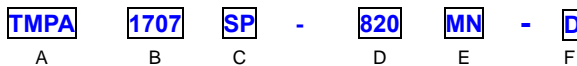
Series	A	A'	B	C	D	E
TMPA1707	17.8±0.5	16.9±0.3	16.9±0.3	6.7±0.3	2.3±0.3	11.9±0.3

Unit:mm

L(mm)	G(mm)	H(mm)
18.5	12.0	12.5

Note: 1. The above PCB layout reference only.
 2. Recommend solder paste thickness at 0.17mm and above.

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: Code
- BxC.
 - Standard.
 - 820=82.0uh.
 - M=±20%.
 - Marking: Black.820 and 1551(15 YY, 51 WW, follow production date).

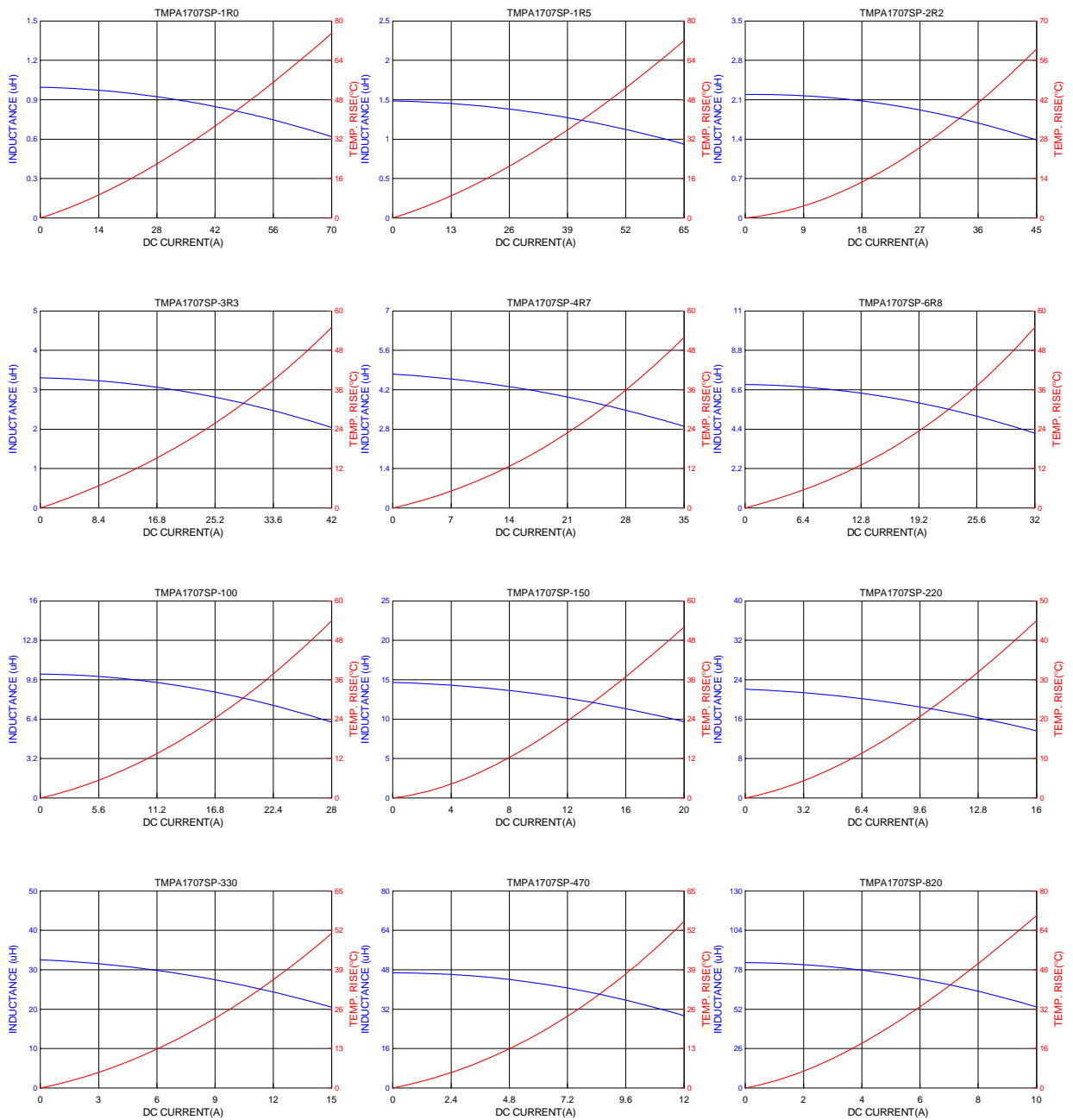
5. Specification

Part Number	Inductance L0 A(uH) ±20%	Heat Rating Current DC (A) I rms.		Saturation Current DC (A) I sat		DCR (mΩ) Typ	DCR (mΩ) Max
		Typ	Max	Typ	Max		
TMPA1707SP-1R0MN-D	1.00	46	42	50	45	1.06	1.3
TMPA1707SP-1R5MN-D	1.50	39	35	46	40	1.5	1.8
TMPA1707SP-2R2MN-D	2.20	32	30	35	32	1.8	2.2
TMPA1707SP-3R3MN-D	3.30	30	28	32	29	2.7	3.3
TMPA1707SP-4R7MN-D	4.70	28	26	29	26	3.7	4.5
TMPA1707SP-6R8MN-D	6.80	24	22	25	22	6.0	7.2
TMPA1707SP-100MN-D	10.0	21	19	22	19	9.2	10.6
TMPA1707SP-150MN-D	15.0	16	14	16	14	12.8	15.5
TMPA1707SP-220MN-D	22.0	13.5	11.5	13.5	11.5	20.5	24
TMPA1707SP-330MN-D	33.0	12	10	12	10	32	37
TMPA1707SP-470MN-D	47.0	9.5	8.0	9.5	8.0	40	47
TMPA1707SP-820MN-D	82.0	6.5	5.7	8.0	6.5	69	83

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves



SMD Power Inductor

TMPA2313SP-Series(N)-D

1. Features

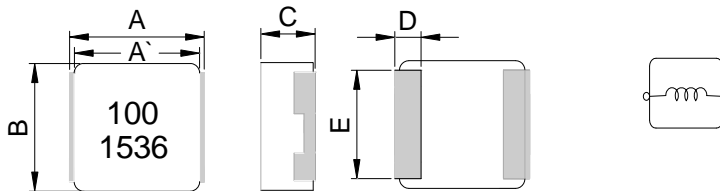
1. Shielded construction.
2. Capable of corresponding high frequency (5MHz).
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.



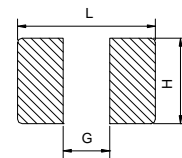
2. Applications

1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

3. Dimensions



Recommend PC Board Pattern



Series	A(mm)	A'(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPA2313	23.5±0.5	22.7±0.3	22.0±0.3	12.6±0.4	5.0±0.4	19.0±0.3

L(mm)	G(mm)	H(mm)
24	12.5	19.6

Note: Recommend solder paste thickness at 0.20mm and above.

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
 - F: Code
- BxC.
 - Standard.
 - 100=10.0uh.
 - M=±20%.
 - Marking: Black.100 and 1536(15 YY, 36 WW, follow production date).

5. Specification

Part Number	Inductance L0 A(μH) ±20%	Heat Rating Current DC (A) Irms.		Saturation Current DC (A)I sat		DCR (mΩ) Typ	DCR (mΩ) Max
		Typ	Max	Typ	Max		
TMPA2313SP-1R5MN-D	1.50	62	57	52	48	1.0	1.15
TMPA2313SP-2R2MN-D	2.20	58	52	48	43	1.05	1.25
TMPA2313SP-3R3MN-D	3.30	49	47	41	37	1.5	1.75
TMPA2313SP-4R7MN-D	4.70	47	44	38	34	1.9	2.2
TMPA2313SP-6R8MN-D	6.80	40	36	36	32	2.7	3.1
TMPA2313SP-100MN-D	10.0	33	30	28	20	3.8	4.15
TMPA2313SP-220MN-D	22.0	22	18	15	14	9.2	11
TMPA2313SP-230MN-D	23.0	22	18	15	14	9.2	11
TMPA2313SP-330MN-D	33.0	19	16	12	10.5	13.5	15.4
TMPA2313SP-470MN-D	47.0	17	14	12	10	17.3	20.8
TMPA2313SP-680MN-D	68.0	14	12	12	9.0	26.2	29.5
TMPA2313SP-750MN-D	75.0	13	11	10.5	8.5	27.5	31.6
TMPA2313SP-820MN-D	82.0	12	10	9.0	7.7	31	34.2
TMPA2313SP-101MN-D	100	11	9.5	9.0	7.5	36	40

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves

